



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/077,452

Filed: February 14, 2002

For: METHOD AND APPARATUS FOR
TRANSFER MOLDING
ENCAPSULATION OF A
SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK

Confirmation No.: 4093

Examiner: D. Graybill

Group Art Unit: 2827

Attorney Docket No.: 2269-3061.6US
(96-0893.05/US)

Notice of Allowance Mailed:

June 22, 2004

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Person making Deposit: Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification appear on page 3 of this paper.

A **Listing of the Claims** begins on page 4 of this paper.

Amendments to the Drawings appear on page 7 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 8 of this paper.

An **Appendix** including amended drawing figures is attached following page 8 of this paper.